



Science
Institutes
&
Industry

worldwide connections fast and
dependable service



Silicon
Wafers
&
Specialty
Services

Our inventory of
Silicon Wafers
from all major manufacturers
will be enlarged
by over 2000 computer
listings of Silicon

Si-Mat Silicon-Materials
Viktor-Frankl-Str. 20
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Silicon Wafer

Prime Monitor Test
CZ and FZ

All Diameters: 1" through 300 mm:
Single- or Double Side Polished
As cut, Lapped, Etched

Orientation: $\langle 100 \rangle$ $\langle 111 \rangle$ $\langle 110 \rangle$

Double Side Polished: 1" through 300 mm:

- Ultra Flat $< 1 \mu\text{m}$ TTV
for 100 mm to 300 mm
SOI, MEMS, Optics
- Precision of thickness $\pm 5 \mu\text{m}$
- Ultra Thin

Thickness: $50 \mu\text{m}$ - $5000 \mu\text{m}$

GaAs
Ge
Pyrex
Fused Quartz
Fused Silica
Glass
Borofloat

SOI Wafer

Silicon on Insulator
Thick Film
Fusion Bonding

Diameters: 3" through 200 mm:
Single- or Double Side Polished
CZ and FZ

Device Layer: Flatness $< 1 \mu\text{m}$ $< 2 \mu\text{m}$ $< 5 \mu\text{m}$
Thickness $< 5 \mu\text{m}$, $10 \mu\text{m}$ to $300 \mu\text{m}$ up

Buried Thermal Oxide: $0,2 \mu\text{m}$ to $2,4 \mu\text{m}$ up

Handle: Flatness $< 1 \mu\text{m}$ up
Any Typ, Orientation, Res.
Thickness $300 \mu\text{m}$ to $2000 \mu\text{m}$

Special

Service

Wafer-Thinning Thermal Oxides SiO_2
Reduction Wafer Size Wet Oxides
Lasermarking Nitride Si_3N_4
Edge Grinding PolySilicon Deposition
Lapping Epitaxy
Thin films, Oxides